

MC100EPT26

3.3V 1:2 Fanout Differential LVPECL/LVDS to LVTTTL Translator

Description

The MC100EPT26 is a 1:2 Fanout Differential LVPECL/LVDS to LVTTTL translator. Because LVPECL (Positive ECL) or LVDS levels are used only +3.3 V and ground are required. The small outline 8-lead package and the 1:2 fanout design of the EPT26 makes it ideal for applications which require the low skew duplication of a signal in a tightly packed PC board.

The V_{BB} output allows the EPT26 to be used in a single-ended input mode. In this mode the V_{BB} output is tied to the $D0$ input for a non-inverting buffer or the $D0$ input for an inverting buffer. If used, the V_{BB} pin should be bypassed to ground with $> 0.01 \mu\text{F}$ capacitor. For a single-ended direct connection, use an external voltage reference source such as a resistor divider. Do not use V_{BB} for a single-ended direct connection or port to another device.

Features

- 1.4 ns Typical Propagation Delay
- Maximum Frequency > 275 MHz Typical
- The 100 Series Contains Temperature Compensation
- Operating Range: $V_{CC} = 3.0$ V to 3.6 V with $GND = 0$ V
- 24 mA TTL outputs
- Q Outputs Will Default LOW with Inputs Open or at V_{EE}
- V_{BB} Output
- Pb-Free Packages are Available



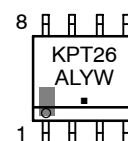
ON Semiconductor®

<http://onsemi.com>

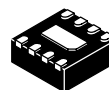
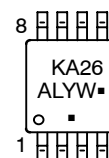
MARKING DIAGRAMS*



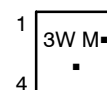
SO-8
D SUFFIX
CASE 751



TSSOP-8
DT SUFFIX
CASE 948R



DFN8
MN SUFFIX
CASE 506AA



- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- M = Date Code
- = Pb-Free Package

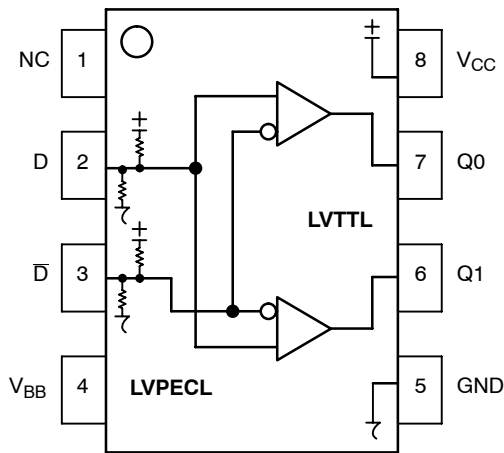
(Note: Microdot may be in either location)

*For additional marking information, refer to Application Note AND8002/D.

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

MC100EPT26



(Top View)

Figure 1. 8-Lead Pinout and Logic Diagram

Table 1. PIN DESCRIPTION

Pin	Function
Q0, Q1	LVTTTL Outputs
D0**, D1**	Differential LVPECL Inputs Pair
V _{CC}	Positive Supply
V _{BB}	Output Reference Voltage
GND	Ground
NC	No Connect
EP	Exposed pad must be connected to a sufficient thermal conduit. Electrically connect to the most negative supply or leave floating open.

** Pins will default to $V_{CC}/2$ when left open.

Table 2. ATTRIBUTES

Characteristics		Value	
Internal Input Pulldown Resistor		50 kΩ	
Internal Input Pullup Resistor		50 kΩ	
ESD Protection	Human Body Model	> 1.5 kV	
	Machine Model	> 100 V	
	Charged Device Model	> 2 kV	
Moisture Sensitivity, Indefinite Time Out of Drypack (Note 1)		Pb Pkg	Pb-Free Pkg
	SO-8	Level 1	Level 1
	TSSOP-8	Level 1	Level 3
	DFN8	Level 1	Level 1
Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	
Transistor Count		117 Devices	
Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test			

1. For additional information, see Application Note AND8003/D.

MC100EPT26

Table 3. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V _{CC}	Positive Power Supply	GND = 0 V		3.8	V
V _{IN}	Input Voltage	GND = 0 V	V _I ≤ V _{CC}	0 to 3.8	V
I _{BB}	V _{BB} Sink/Source			± 0.5	mA
T _A	Operating Temperature Range			-40 to +85	°C
T _{stg}	Storage Temperature Range			-65 to +150	°C
θ _{JA}	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	SOIC-8 SOIC-8	190 130	°C/W °C/W
θ _{JC}	Thermal Resistance (Junction-to-Case)	Standard Board	SOIC-8	41 to 44	°C/W
θ _{JA}	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	TSSOP-8 TSSOP-8	185 140	°C/W °C/W
θ _{JC}	Thermal Resistance (Junction-to-Case)	Standard Board	TSSOP-8	41 to 44	°C/W
θ _{JA}	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	DFN8 DFN8	129 84	°C/W °C/W
T _{sol}	Wave Solder Pb Pb-Free			265 265	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Table 4. PECL INPUT DC CHARACTERISTICS V_{CC} = 3.3 V; GND = 0.0 V (Note 2)

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
V _{IH}	Input HIGH Voltage (Single-Ended)	2075		2420	2075		2420	2075		2420	mV
V _{IL}	Input LOW Voltage (Single-Ended)	1355		1675	1355		1675	1355		1675	mV
V _{BB}	Output Voltage Reference	1910	2035	2160	1910	2035	2160	1910	2035	2160	V
V _{IHCMR}	Input HIGH Voltage Common Mode Range (Differential) (Note 3)	1.2		3.3	1.2		3.3	1.2		3.3	V
I _{IH}	Input HIGH Current			150			150			150	μA
I _{IL}	Input LOW Current	D D̄	-150 -150		-150 -150			-150 -150			μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

2. Input parameters vary 1:1 with V_{CC}.

3. V_{IHCMR} min varies 1:1 with GND, V_{IHCMR} max varies 1:1 with V_{CC}. The V_{IHCMR} range is referenced to the most positive side of the differential input signal.

Table 5. TTL OUTPUT DC CHARACTERISTICS V_{CC} = 3.3 V; GND = 0.0 V; T_A = -40°C to 85°C

Symbol	Characteristic	Condition	Min	Typ	Max	Unit
V _{OH}	Output HIGH Voltage	I _{OH} = -3.0 mA	2.4			V
V _{OL}	Output LOW Voltage	I _{OL} = 24 mA			0.5	V
I _{CCH}	Power Supply Current		10	20	18	mA
I _{CCL}	Power Supply Current		15	28	35	mA
I _{OS}	Output Short Circuit Current		-50		-150	mA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

MC100EPT26

Table 6. AC CHARACTERISTICS $V_{CC} = 3.0\text{ V to }3.6\text{ V}$; $GND = 0.0\text{ V}$ (Note 4)

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
f_{max}	Maximum Frequency (Figure 2)	275	350		275	350		275	350		MHz
t_{PLH} , t_{PHL}	Propagation Delay to Output Differential (Note 5)	1.2	1.5	2.0	1.2	1.5	2.0	1.3	1.7	2.2	ns
t_{SK++} , t_{SK--} , t_{SKPP}	Within Device Skew++ Within Device Skew-- Device-to-Device Skew (Note 6)		15	60		15	60		20	85	ps
t_{JITTER}	Random Clock Jitter (RMS) (Figure 2) @ $\leq 200\text{ MHz}$ @ $> 200\text{ MHz}$		6	30		6	30		6	30	ps
V_{PP}	Input Voltage Swing (Differential Configuration)	150	800	1200	150	800	1200	150	800	1200	mV
t_r , t_f	Output Rise/Fall Times (0.8V – 2.0V) Q, \bar{Q}	330	600	950	330	600	950	330	650	950	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

4. Measured with a 750 mV 50% duty-cycle clock source. $R_L = 500\ \Omega$ to GND and $C_L = 20\text{ pF}$ to GND. Refer to Figure 3.
5. Reference ($V_{CC} = 3.3\text{ V} \pm 5\%$; $GND = 0\text{ V}$)
6. Skews are measured between outputs under identical transitions.

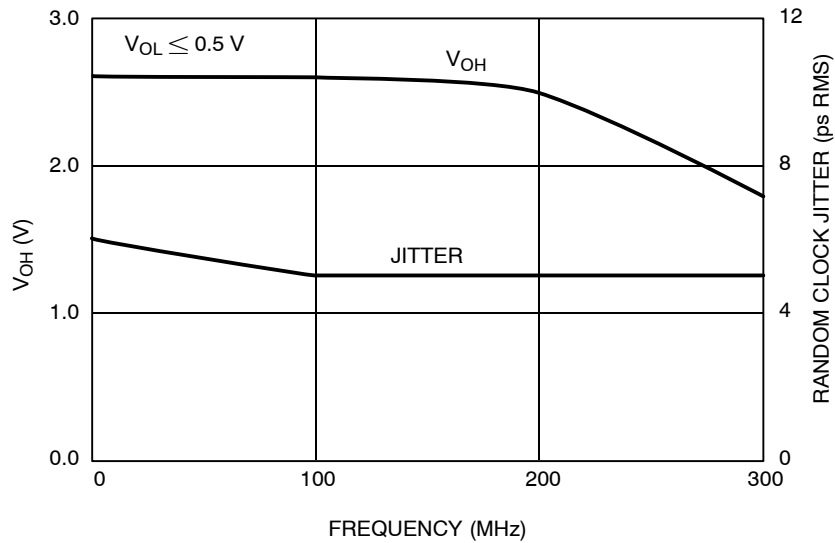


Figure 2. Typical V_{OH} / Jitter versus Frequency (25°C)

MC100EPT26

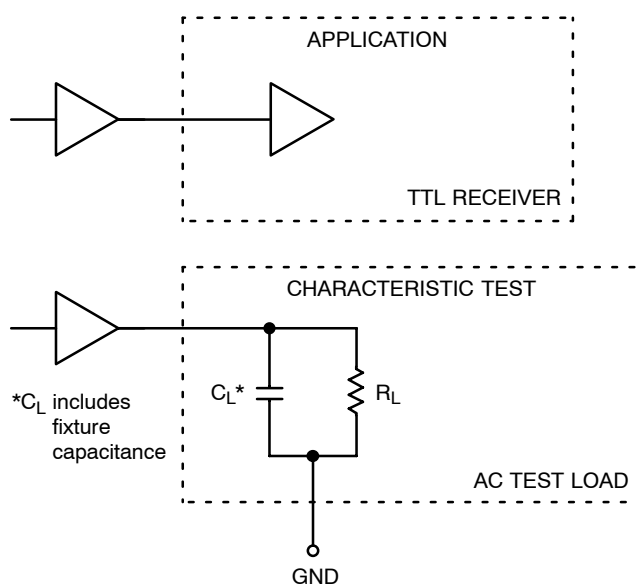


Figure 3. TTL Output Loading Used for Device Evaluation

ORDERING INFORMATION

Device	Package	Shipping [†]
MC100EPT26D	SOIC-8	98 Units / Rail
MC100EPT26DG	SOIC-8 (Pb-Free)	98 Units / Rail
MC100EPT26DR2	SOIC-8	2500 / Tape & Reel
MC100EPT26DR2G	SOIC-8 (Pb-Free)	2500 / Tape & Reel
MC100EPT26DT	TSSOP-8	100 Units / Rail
MC100EPT26DTG	TSSOP-8 (Pb-Free)	100 Units / Rail
MC100EPT26DTR2	TSSOP-8	2500 / Tape & Reel
MC100EPT26DTR2G	TSSOP-8 (Pb-Free)	2500 / Tape & Reel
MC100EPT26MNR4	DFN8	1000 / Tape & Reel
MC100EPT26MNR4G	DFN8 (Pb-Free)	1000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MC100EPT26

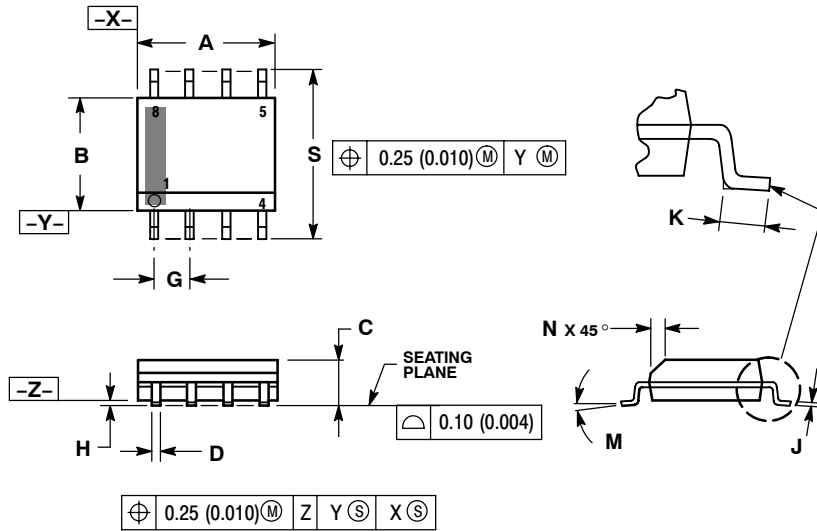
Resource Reference of Application Notes

- AN1405/D** – ECL Clock Distribution Techniques
- AN1406/D** – Designing with PECL (ECL at +5.0 V)
- AN1503/D** – ECLinPS™ I/O SPiCE Modeling Kit
- AN1504/D** – Metastability and the ECLinPS Family
- AN1568/D** – Interfacing Between LVDS and ECL
- AN1672/D** – The ECL Translator Guide
- AND8001/D** – Odd Number Counters Design
- AND8002/D** – Marking and Date Codes
- AND8020/D** – Termination of ECL Logic Devices
- AND8066/D** – Interfacing with ECLinPS
- AND8090/D** – AC Characteristics of ECL Devices

MC100EPT26

PACKAGE DIMENSIONS

SOIC-8 NB
CASE 751-07
ISSUE AH

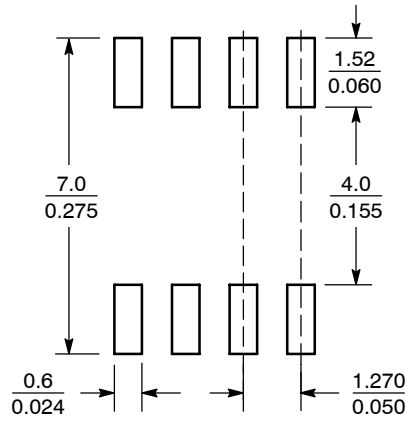


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. 751-01 THRU 751-06 ARE OBSOLETE. NEW STANDARD IS 751-07.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.80	5.00	0.189	0.197
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.053	0.069
D	0.33	0.51	0.013	0.020
G	1.27 BSC		0.050 BSC	
H	0.10	0.25	0.004	0.010
J	0.19	0.25	0.007	0.010
K	0.40	1.27	0.016	0.050
M	0°	8°	0°	8°
N	0.25	0.50	0.010	0.020
S	5.80	6.20	0.228	0.244

SOLDERING FOOTPRINT*



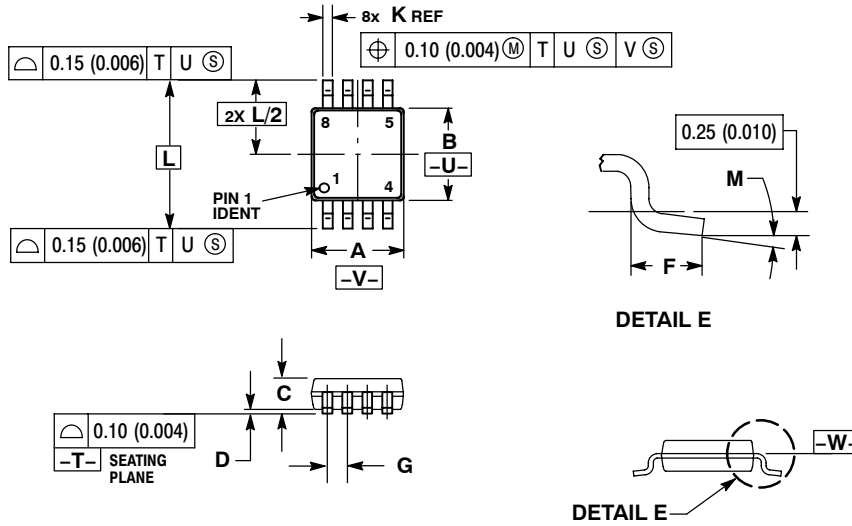
SCALE 6:1 $\left(\frac{\text{mm}}{\text{inches}}\right)$

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MC100EPT26

PACKAGE DIMENSIONS

TSSOP-8
DT SUFFIX
 PLASTIC TSSOP PACKAGE
 CASE 948R-02
 ISSUE A



NOTES:

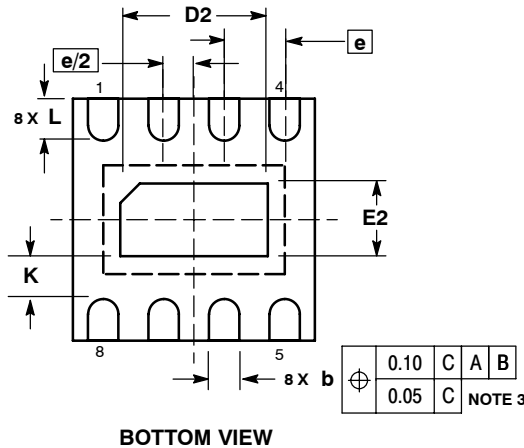
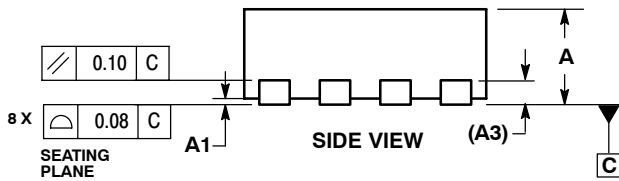
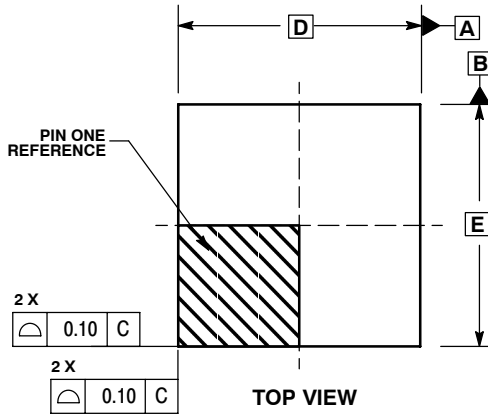
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
6. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.90	3.10	0.114	0.122
B	2.90	3.10	0.114	0.122
C	0.80	1.10	0.031	0.043
D	0.05	0.15	0.002	0.006
F	0.40	0.70	0.016	0.028
G	0.65 BSC		0.026 BSC	
K	0.25	0.40	0.010	0.016
L	4.90 BSC		0.193 BSC	
M	0°	6°	0°	6°

MC100EPT26

PACKAGE DIMENSIONS

DFN8
CASE 506AA-01
ISSUE D




NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994 .
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.80	1.00
A1	0.00	0.05
A3	0.20 REF	
b	0.20	0.30
D	2.00 BSC	
D2	1.10	1.30
E	2.00 BSC	
E2	0.70	0.90
e	0.50 BSC	
K	0.20	---
L	0.25	0.35

ECLinPS is a trademark of Semiconductor Components Industries, LLC (SCILLC).

ON Semiconductor and  are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:
Literature Distribution Center for ON Semiconductor
P.O. Box 5163, Denver, Colorado 80217 USA
Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada
Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada
Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free
USA/Canada
Europe, Middle East and Africa Technical Support:
Phone: 421 33 790 2910
Japan Customer Focus Center
Phone: 81-3-5773-3850

ON Semiconductor Website: www.onsemi.com
Order Literature: <http://www.onsemi.com/orderlit>
For additional information, please contact your local Sales Representative